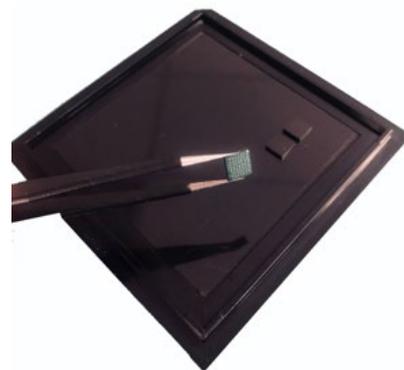


## VERTEC® BUMPED DIE CARRIER FILM (GP-BMP)

### Preliminary Product Datasheet

- For bumped die, flip chip and BGA handling.
- Protects fragile solder bumps during handling and transport.
- Flat film surface able to hold bumped devices "bump side down" and easily release.
- Compatible with automated pick & place equipment.
- Can be provided in multiple carrier form factors such as JEDEC standard trays, 2", 4", flat matrix or customer specific substrates.
- Available in sheet and roll format.

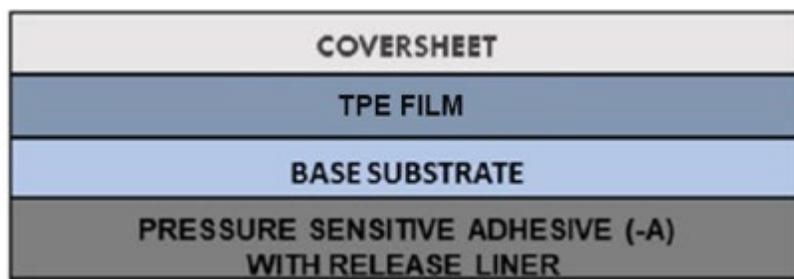


Properties	Value
Compatible Device Bump Height	60µm to 160µm
Elastomer Color	Translucent*
ESD SR	> E12 (ohms)
Operating Temperature	+10 to +35° C
Storage Temperature	-10 to +50° C
Shelf Life	2 Years
Unique Features	Silicone Free

3 +/-10% mils

3 +/- 3% mils

See PSA Thickness Table



Pressure Sensitive Adhesive (PSA) Thickness Table

PSA Type	Nominal Thickness
Black (standard)	8.1 mils
White (optional)	5.0 mils

\* Elastomer Color is translucent, but the surface appearance will depend upon the pressure sensitive adhesive color. Black pressure sensitive adhesive is standard and white is an option. Note: White based PSA BMP material allows for printed location grids. These values are for reference purposes only and are not intended for use in preparing specifications.

### GEL-PAK

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